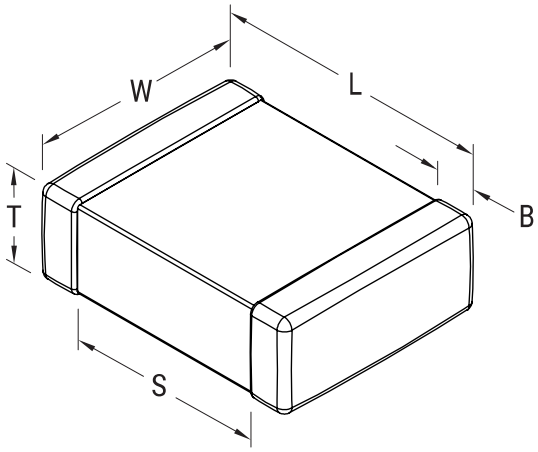
C1206X829D2TACTU

Aliases (C1206X829D2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 8.2 pF, +/-0.5 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	0.78mm +/-0.20mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	8.2 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.5 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms